



AF  
1753  
Rw

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Jung-Chih HU et al.

Confirmation No.: 5769

Serial No.: 10/070,000

Examiner: Edna Wong

Filed: November 27, 2002

Group Art Unit: 1753

Title: ELECTROPLATING SOLUTION FOR COPPER ELECTROPLATING

**REPLY AFTER FINAL REJECTION**

**MAIL STOP AF**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the final Office Action mailed March 10, 2004, kindly amend the above-identified application as follows.

Amendments and additions to the **Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.